

LISTING OF THE CLAIMS:

1. (Currently Amended) A substrate having at least two metallized polymer studs for soldered connections to a wiring and having conductor runs which lead away from the polymer studs on a lower face of the substrate, each of the polymer studs having ~~at least one step in order to form~~ an end with at least one projection extending beyond an end surface of the rest of the stud to form a step at the end of the stud.--

2. (Previously Presented) The substrate according to claim 1, wherein the projection is a cylindrical projection which is arranged concentrically with respect to the polymer stud.

3. (Currently Amended) ~~The~~ A ~~substrate according to claim 2, wherein having~~ at least two metallized polymer studs for soldered connections to a wiring and having conductor runs which lead away from the polymer studs on a lower face of the substrate, each of the polymer studs having a step in order to form a cylindrical projection which is arranged concentrically with respect to the polymer stud, the cylindrical projection ~~has~~ having a diameter of between 100 μ m and 300 μ m, and a height of between 25 μ m and 250 μ m.

4. (Previously Presented) The substrate according to claim 1, wherein the polymer studs are provided with two projections forming two steps.

5. (Previously Presented) The substrate according to claim 1, wherein the polymer studs are provided with a number of projections arranged at a distance from one another on the step.

Claim 6 (cancelled).

7. (New) The substrate according to claim 1, wherein the projection is an annular projection.